Supertex inc.

High-Voltage Ring Generator

Features

- 105Vrms ring signal
- Output over current protection
- ► 5.0V CMOS logic control
- Logic enable/disable to save power
- Adjustable deadband in single-control mode
- Power-on reset
- Fault output for problem detection

Applications

- Line access cards
- Set-top/Street box

General Description

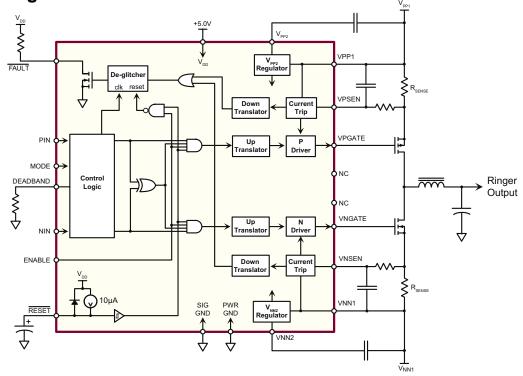
The Supertex HV430 is a high voltage PWM ring generator integrated circuit. The high voltage outputs, V_{PGATE} and V_{NGATE} , are used to drive the gates of external high voltage N-channel and P-channel MOSFETs in a push-pull configuration. Overcurrent protection is implemented for both the P-channel and N-channel MOSFETs. External sense resistors set the over-current trip point.

Functional Block Diagram

The RESET input functions as a power-on reset when connected to an external capacitor. The FAULT output indicates an over-current condition and is cleared after 4 consecutive cycles with no overcurrent condition. A logic low on RESET or ENABLE clears the FAULT output. It is active-low and open-drain to allow wire OR'ing of multiple drivers.

 P_{GATE} and N_{GATE} are controlled independently by logic inputs P_{IN} and N_{IN} when the MODE pin is at logic high. A logic high on P_{IN} will turn on the external P-channel MOSFET. Similarly, a logic high on N_{IN} will turn on the external N-channel MOSFET. Lockout circuitry prevents the N and P switches from turning on simultaneously. A pulse width limiter restricts pulse widths to no less than 100 - 200ns.

For applications where a single control input is desired, the MODE pin should be connected to SGND. The PWM control signal is then input to the N_{IN} pin. A user-adjustable deadband in the control logic ensures break-before-make on the outputs, thus avoiding cross conduction on the high voltage output during switching. A logic high on N_{IN} will turn the external P-Channel MOSFET on and the N-Channel off, and vice versa. The IC can be powered down by applying a logic low on the ENABLE pin, placing both external MOSFETs in the off state.



Ordering Information

	Package Option
Device	20-Lead SOW 12.80x7.50mm body 2.65mm height (max) 1.27mm pitch
HV430	HV430WG-G



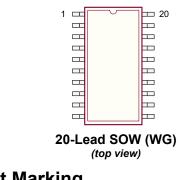
Pin Configuration

-G indicates package is RoHS compliant ('Green')

Absolute Maximum Ratings

Parameter	Value
V_{PP1} - V_{NN1} , power supply voltage	+340V
$V_{_{\rm PP1}}$, positive high voltage supply	+220V
$V_{_{PP2}}$, positive gate voltage supply	+220V
$V_{_{\rm NN1}}$, negative high voltage supply	-220V
$V_{_{NN2}}$, negative gate voltage supply	-220V
V _{DD} , logic supply	+7.5V
Storage temperature	-65°C to +150°C
Power dissipation	600mW

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



Product Marking



Package may or may not include the following marks: Si or (f) 20-Lead SOW (WG)

Electrical Characteristics (Over operating supply voltage unless otherwise specified. $T_A = -40^{\circ}C$ to +85°C)

Sym	Parameter	Min	Тур	Мах	Units	Conditions
Externa	Supplies					
V _{PP1}	High voltage positive supply	50	-	200	V	
I _{PP1Q}	V _{PP1} quiescent current	-	250	500	μA	$P_{IN} = N_{IN} = 0V$
I _{PP1}	V _{PP1} operating current	-	-	2.0	mA	No load, V_{outp} and V_{outn} switching at 100KHz
V _{NN1}	High voltage negative supply	V _{PP1} -325	-	-50	V	
I _{NN1Q}	V _{NN1} quiescent current	-	250	500	μA	$P_{IN} = N_{IN} = 0V, R_{DB} = 18k\Omega$
I _{NN1}	V _{NN1} operating current	-	-	1.0	mA	No load, $V_{_{OUTP}} and V_{_{OUTN}}$ switching at 100KHz
V _{DD}	Logic supply voltage	4.50	-	5.50	V	
I _{DDQ}	V _{DD} quiescent current	-	300	400	μA	$P_{IN} = N_{IN} = 0V, R_{DB} = 18k\Omega$
I _{DD}	V _{DD} operating current	-	-	1.0	mA	$P_{IN} = N_{IN} = 100 \text{KHz},$ $R_{DB} = 18 \text{k}\Omega$

Electrical Characteristics (cont.)(Over operating supply voltage unless otherwise specified. T_A = -40°C to +85°C)

Sym	Parameter	Min	Тур	Max	Units	Conditions	
Internal	Supplies		•	•	•		
$V_{_{PP2}}$	Positive linear regulator output voltage	V _{PP1} -16	-	V _{PP1} -10	V		
V _{NN2}	Negative linear regulator output voltage	V _{PP1} +10	-	V _{PP1} +14	V		
Positive	High Voltage Output						
V_{PGATE}	Output voltage swing	V _{PP2}	-	V _{PP1}	V	No load on V _{PGATE}	
R	V_{PGATE} source resistance	-	-	12.5	Ω	I _{оит} = 80mA	
R_{SINKP}	V _{PGATE} sink resistance	-	-	12.5	Ω	I _{оит} = -80mA	
t _{RISEP}	V _{PGATE} rise time	-	-	50	ns	C _{LOAD} = 1.4nF	
t _{FALLP}	V _{PGATE} fall time	-	-	50	ns	C _{LOAD} = 1.4nF	
t _{PWP(MIN)}	V _{PGATE} minimum pulse width (internally limited)	100	150	200	ns		
t _{DELAYP}	P _{IN} to P _{GATE} delay time	-	-	300	ns	Mode = 1	
V _{PSEN}	V _{PGATE} current sense voltage	V _{PP1} -0.85	V _{PP1} -1.0	V _{PP1} -1.15	V		
t _{shortp}	V _{PGATE} current sense off time	-	-	150	ns		
	e High Voltage Output						
V _{NGATE}	Output voltage swing	V _{NN2}	-	V _{NN1}	V	No load on V _{NGATE}	
R	V _{NGATE} source resistance	-	-	15.0	Ω	I _{оυт} = 80mA	
R _{SINKN}	V _{NGATE} sink resistance	-	-	15.0	Ω	I _{оυт} = 80mA	
t _{risen}	V _{NGATE} rise time	-	-	50	ns	C _{LOAD} = 1.4nF	
t _{FALLN}	V _{NGATE} fall time	-		- 50		C _{LOAD} = 1.4nF	
t _{pwn(MIN)}	V _{NGATE} minimum pulse width (internally limited)	100	150	200	ns		
t _{DELAYN}	N _{IN} to N _{GATE} delay time	-	-	300	ns	Mode = 1	
V _{NSEN}	V _{NGATE} current sense voltage	V _{NN1} +0.85	V _{NN1} +1.0	V _{NN1} +1.15	V		
t _{shortn}	V _{NGATE} current sense off time	-	-	150	ns		
	Circuitry	·					
V _{IL}	Logic input low voltage	0	-	0.60	V	V _{DD} = 5.0V	
V _{IH}	Logic input high voltage	2.7	-	5.0	V	$V_{DD} = 5.0V$	
I _{INDN}	Input pull-down current	0.5	1.0	5.0	μA	P _{IN} , N _{IN} , ENABLE	
R _{UP}	Input pull-up resistance	100	200	300	ΚΩ	MODE	
V _{OL}	Logic output low voltage	-	-	0.50	V	V _{DD} = 5.0V, I _{OUT} = -0.5mA	
V _{OH}	Logic output high voltage	4.50	-	-	V	$V_{DD} = 5.0V, I_{OUT} = +0.5m$	
V _{RST(OFF)}	RESET voltage, device off	3.2	-	3.5	V	V _{DD} = 5.0V	
V _{RST(ON)}	RESET voltage, device on	3.7	_	4.0	V	V _{DD} = 5.0V	

Sym	Parameter	Min	Тур	Max	Units	Conditions
V _{RST(HYS)}	RESET hysteresis voltage	0.3	-	-	V	V _{DD} = 5.0V
I _{RESET}	RESET pull-up current	7.0	10	13	μA	V _{RESET} = 0 - 4.5V
t _{RST(ON)}	RESET on delay	-	-	1.0	μs	
t _{RST(ON)}	RESET off delay	-	-	1.0	μs	
t _{EN(ON)}	ENABLE on delay	50	100	150	μs	
t _{EN(OFF)}	ENABLE off delay	-	-	1.0	μs	
t _{flt(hold)}	FAULT hold time	-	4	-	N _{IN} /P _{IN} cycles	ENABLE = 1
+	Deadband time	35	50	70		Mode = 0, R_{DB} = 5.6k Ω
t _{DB}		105	140	175	ns	Mode = 0, R_{DB} = 18k Ω
t _{DELAY(N-P)}	N-off to P-on transistion delay	-	-	300	ns	Mode = 0, $R_{DB} < 27k\Omega$
t _{DELAY(P-N)}	P-off to N-on transistion delay	-	-	300	ns	Mode = 0, R_{DB} < 27k Ω
$\Delta t_{\text{DELAY(N-P)}}$	Delay difference: $t_{delayN(off)} - t_{delayP(on)}$	-80	0	80	ns	Mode = 1
$\Delta t_{\text{DELAY(P-N)}}$	Delay difference: t _{delayP(off)} - t _{delayN(on)}	-80	0	80	ns	Mode = 1

Electrical Characteristics (cont.) (over operating supply voltage unless otherwise specified. $T_{a} = -40^{\circ}$ C to +85°C)

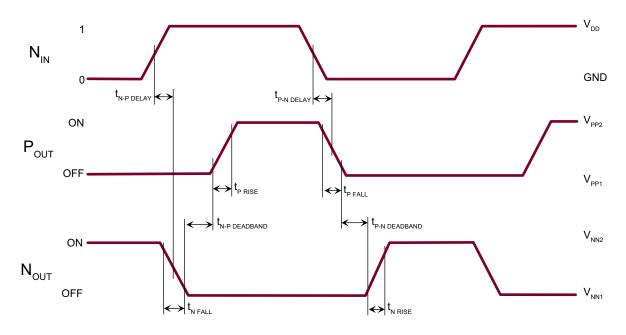
Truth Table

	Logic	Inputs*			Output				
N _{IN}	P _{IN}	Mode	EN	RESET	Externel N-Channel MOSFET	Externel P-Channel MOSFET			
L	L	Н	Н	>V _{RESET(ON)}	OFF	OFF			
L	Н	Н	Н	>V _{RESET(ON)}	OFF	ON			
Н	L	Н	Н	>V _{RESET(ON)}	ON	OFF			
Н	Н	Н	Н	>V _{RESET(ON)}	OFF	OFF			
Н	Х	L	Н	>V _{RESET(ON)}	OFF	ON			
L	Х	L	Н	>V _{RESET(ON)}	ON	OFF			
Х	Х	Х	L	X	OFF	OFF			
Х	Х	X	Х	<v<sub>RESET(OFF)</v<sub>	OFF	OFF			

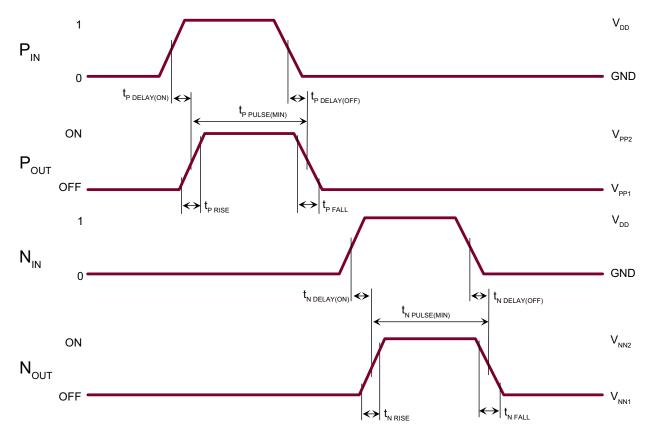
Note:

* Unused logic inputs should be connected to VDD or GND.

Single-Control Mode Timing

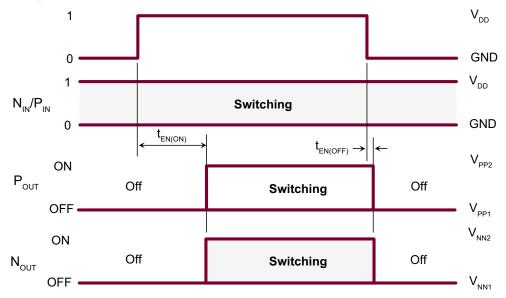


Dual-Control Mode Timing

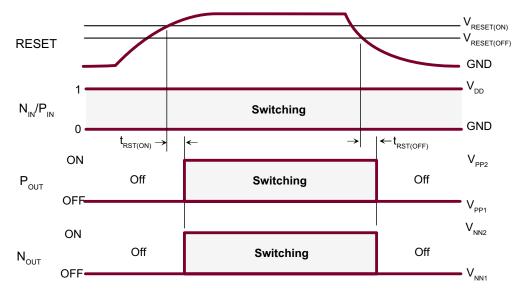


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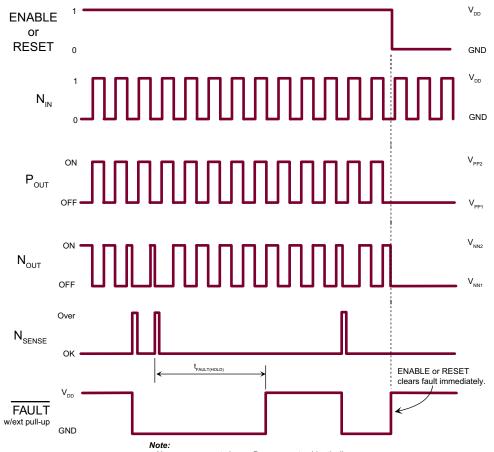
ENABLE Timing



RESET Timing



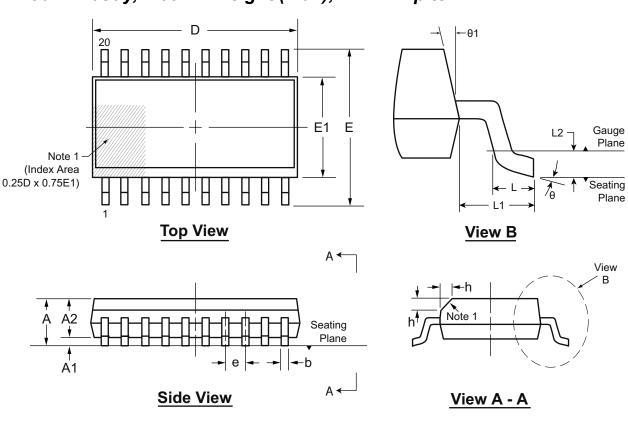
FAULT Timing



 $N_{\rm sense}$ overcurrent shown. $P_{\rm sense}$ operates identically.

Pin Description

Pin #	Name	Description
1	VDD	Logic supply voltage.
2	FAULT	Logic output. Fault is at logic low when either current limit sense pin, VPSEN or VNSEN, is activated. Remains active until overcurrent condition clears or ENABLE = 0 or RESET = 0.
3	MODE	Logic mode input. 0 = single-control; 1 = dual-control. When MODE is high, NIN and PIN independently control N_{OUT} and P_{OUT} , respectively. When MODE is low, NIN controls both outputs in a complementary manner. (See Truth Table)
4	PIN	Logic control input. When mode is high, logic input high turns on the external high voltage P-chan- nel MOSFET. Internally pulled low.
5	NIN	Logic control input. When mode is high, logic input high turns on the external high voltage N-chan- nel MOSFET. Internally pulled low.
6	ENABLE	Logic enable input. Logic high enables IC. Internally pulled low.
7	RESET	Power-on reset. A capacitor connected between this pin and ground determines the delay time between application of VDD and when the device outputs are enabled. Low leakage tantalum recommended.
8	DEADBAND	A resistor between this pin and ground sets the 'break-before-make' time between output transi- tions. Applicable only in single-control mode. For minimum deadtime, a $5.6k\Omega$ resistor to ground should be used. For dual-input mode, tie to VDD.
9	SGND	Low voltage logic ground.
10	PGND	High voltage logic ground.
11	VNN2	Negative gate voltage supply. Generated by an internal linear regulator. A 25V, 100nF capacitor should beconnected between VNN2 and VNN1.
12	VNN1	Negative high voltage supply.
13	VNSEN	Pulse by pulse over current sensing for N-Channel MOSFET.
14	VNGATE	Gate drive for external N-channel MOSFET.
15	N/C	No connect.
16	IN/C	
17	VPGATE	Gate drive for external P-channel MOSFET.
18	VPSEN	Pulse by pulse over current sensing for P-Channel MOSFET.
19	VPP1	Positive high voltage supply.
20	VPP2	Positive gate voltage supply. Generated by an internal linear regulator. A 25V, 100nF capacitor should beconnected between VPP2 and VPP1.



20-Lead SOW (Wide Body) Package Outline (WG) 12.80x7.50mm body, 2.65mm height (max), 1.27mm pitch

Note:

1. A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or a printed indicator.

Symbo	ol	Α	A1	A2	b	D	E	E1	е	h	L	L1	L2	θ	θ1
Dimension (mm)	MIN	2.15*	0.10	2.05	0.31	12.60*	9.97*	7.40*		0.25	0.40			0 0	5 °
	NOM	-	-	-	-	12.80	10.30	7.50	1.27 BSC	-	-	1.40 REF	0.25 BSC	-	-
	MAX	2.65	0.30	2.55*	0.51	13.00*	10.63*	7.60*		0.75	1.27			8 0	15 ⁰

JEDEC Registration MS-013, Variation AC, Issue E, Sep. 2005.

* This dimension is not specified in the JEDEC drawing.

Drawings are not to scale.

Supertex Doc. #: DSPD-20SOWWG, Version D041309.

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information go to <u>http://www.supertex.com/packaging.html</u>.)

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